# NLSV4T244E

# 4-Bit Dual-Supply Non-Inverting Level Translator

The NLSV4T244E is a 4−bit configurable dual−supply voltage level translator. The input $A_n$ and output $B_n$ ports are designed to track two different power supply rails, $V_{CCA}$ and $V_{CCB}$ respectively. Both supply rails are configurable from 0.9 V to 4.5 V allowing universal low−voltage translation from the input $A_n$ to the output $B_n$ port.

### Features

- Wide $V_{CCA}$ and $V_{CCB}$ Operating Range: 0.9 V to 4.5 V
- High−Speed w/ Balanced Propagation Delay
- Inputs and Outputs have OVT Protection to 4.5 V
- Non−preferential $V_{CCA}$ and $V_{CCB}$ Sequencing
- Outputs at 3−State until Active $V_{CC}$ is Reached
- Power−Off Protection
- Outputs Switch to 3−State with $V_{CCB}$ at GND
- Data Rate > 200 Mbps @ $V_{CCA}$ = 1.8 V, $V_{CCB}$ = 3.3 V, $R_L$ = 2 kΩ, $C_L$ = 15 pF
- Ultra−Small Packaging: 1.7 mm x 2.0 mm UQFN12
- These are Pb−Free Devices

### Typical Applications

- Mobile Phones, PDAs, Other Portable Devices

### Important Information

- ESD Protection for All Pins:
  HBM (Human Body Model) > 2000 V
  MM (Machine Model) > 400 V

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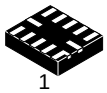
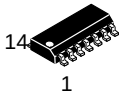
### MARKING DIAGRAMS

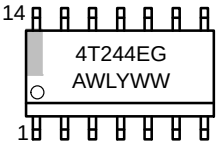


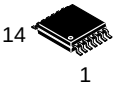

**UQFN12**
**MU SUFFIX**
**CASE 523AE**


AF = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

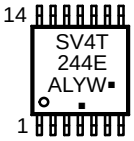



**SOIC−14**
**D SUFFIX**
**CASE 751A**




**TSSOP−14**
**DT SUFFIX**
**CASE 948G**




| | | |
|---|---|---|
| A | = | Assembly Location |
| L, WL | = | Wafer Lot |
| Y, YY | = | Year |
| W, WW | = | Work Week |
| G or ▪ | = | Pb−Free Package |

(Note: Microdot may be in either location)

### ORDERING INFORMATION

| Device | Package | Shipping† |
|---|---|---|
| NLSV4T244EMUTAG | UQFN12 (Pb−Free) | 3000/Tape & Reel |
| NLSV4T244EDR2G | SO−14 (Pb−Free) | 2500/Tape & Reel |
| NLSV4T244EDTR2G | TSSOP14 (Pb−Free) | 2500/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

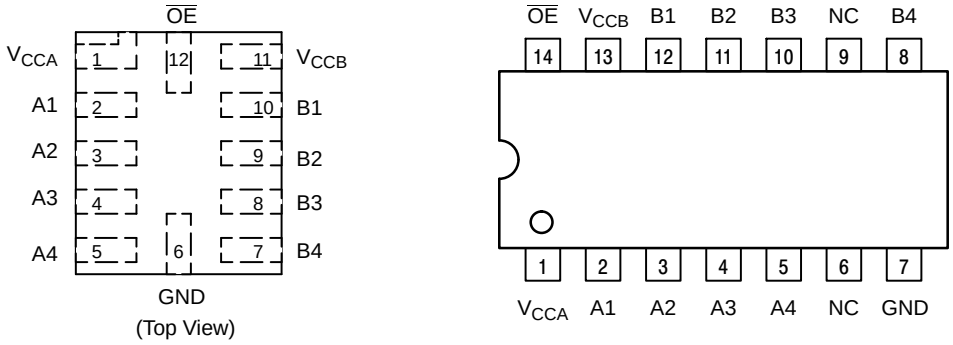



**Figure 1. Pin Assignments**

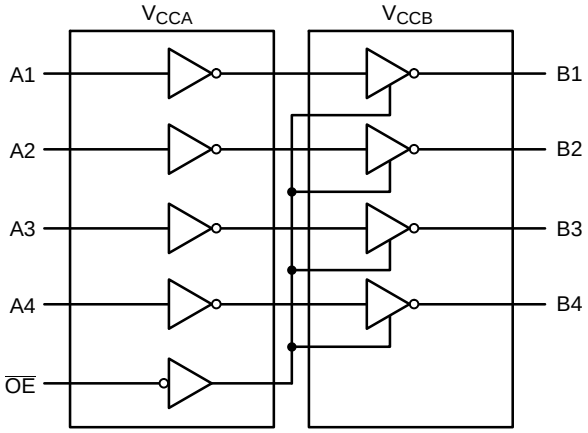



**Figure 2. Logic Diagram**

**PIN ASSIGNMENT**

| PIN | FUNCTION |
|---|---|
| $V_{CCA}$ | Input Port DC Power Supply |
| $V_{CCB}$ | Output Port DC Power Supply |
| GND | Ground |
| $A_n$ | Input Port |
| $B_n$ | Output Port |
| $\overline{OE}$ | Output Enable |

**TRUTH TABLE**

| Inputs | | Outputs |
|---|---|---|
| $\overline{OE}$ | $A_n$ | $B_n$ |
| L | L | L |
| L | H | H |
| H | X | 3−State |

## MAXIMUM RATINGS

| Symbol | Rating | | Condition | Value | Unit |
|---|---|---|---|---|---|
| $V_{CCA}$, $V_{CCB}$ | DC Supply Voltage | | | −0.5 to +5.5 | V |
| $V_I$ | DC Input Voltage | $A_n$ | | −0.5 to +5.5 | V |
| $V_C$ | Control Input | $\overline{OE}$ | | −0.5 to +5.5 | V |
| $V_O$ | DC Output Voltage (Power Down) | $B_n$ | $V_{CCA} = V_{CCB} = 0$ | −0.5 to +5.5 | V |
| | (Active Mode) | $B_n$ | | −0.5 to +5.5 | V |
| | (Tri−State Mode) | $B_n$ | | −0.5 to +5.5 | V |
| $I_{IK}$ | DC Input Diode Current | | $V_I$ < GND | −20 | mA |
| $I_{OK}$ | DC Output Diode Current | | $V_O$ < GND | −50 | mA |
| $I_O$ | DC Output Source/Sink Current | | | ±50 | mA |
| $I_{CCA}$, $I_{CCB}$ | DC Supply Current Per Supply Pin | | | ±100 | mA |
| $I_{GND}$ | DC Ground Current per Ground Pin | | | ±100 | mA |
| $T_{STG}$ | Storage Temperature Range | | | −65 to +150 | °C |
| $T_J$ | Junction Temperature | | | +125 | °C |
| $\theta_{JA}$ | Junction−to−Ambient Thermal Resistance | | | 53 | °C/W |
| $\Psi_{JC(top)}$ | Junction−to−Case (Top) Thermal Resistance | | | 10 | °C/W |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | | Min | Max | Unit |
|---|---|---|---|---|---|
| $V_{CCA}$, $V_{CCB}$ | Positive DC Supply Voltage | | 0.9 | 4.5 | V |
| $V_I$ | Bus Input Voltage | | GND | 4.5 | V |
| $V_C$ | Control Input | $\overline{OE}$ | GND | 4.5 | V |
| $V_{IO}$ | Bus Output Voltage (Power Down Mode) | $B_n$ | GND | 4.5 | V |
| | (Active Mode) | $B_n$ | GND | $V_{CCB}$ | V |
| | (Tri−State Mode) | $B_n$ | GND | 4.5 | V |
| $T_A$ | Operating Temperature Range | | −40 | +85 | °C |
| $\Delta t / \Delta V$ | Input Transition Rise or Rate<br>$V_I$, from 30% to 70% of $V_{CC}$; $V_{CC}$ = 3.3 V ±0.3 V | | 0 | 10 | nS |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Test Conditions | $V_{CCA}$ (V) | $V_{CCB}$ (V) | −40°C to +85°C | | Unit |
|---|---|---|---|---|---|---|---|
| | | | | | Min | Max | |
| $V_{IH}$ | Input HIGH Voltage (An, $\overline{OE}$) | | 3.6 – 4.5 | 0.9 – 4.5 | 2.2 | – | V |
| | | | 2.7 – 3.6 | | 2.0 | – | |
| | | | 2.3 – 2.7 | | 1.6 | – | |
| | | | 1.4 – 2.3 | | 0.65 * $V_{CCA}$ | – | |
| | | | 0.9 – 1.4 | | 0.9 * $V_{CCA}$ | – | |
| $V_{IL}$ | Input LOW Voltage (An, $\overline{OE}$) | | 3.6 – 4.5 | 0.9 – 4.5 | – | 0.8 | V |
| | | | 2.7 – 3.6 | | – | 0.8 | |
| | | | 2.3 – 2.7 | | – | 0.7 | |
| | | | 1.4 – 2.3 | | – | 0.35 * $V_{CCA}$ | |
| | | | 0.9 – 1.4 | | – | 0.1 * $V_{CCA}$ | |
| $V_{OH}$ | Output HIGH Voltage | $I_{OH}$ = −100 μA; $V_I$ = $V_{IH}$ | 0.9 – 4.5 | 0.9 – 4.5 | $V_{CCB}$ – 0.2 | – | V |
| | | $I_{OH}$ = −0.5 mA; $V_I$ = $V_{IH}$ | 0.9 | 0.9 | 0.75 * $V_{CCB}$ | – | |
| | | $I_{OH}$ = −2 mA; $V_I$ = $V_{IH}$ | 1.4 | 1.4 | 1.05 | – | |
| | | $I_{OH}$ = −6 mA; $V_I$ = $V_{IH}$ | 1.65 | 1.65 | 1.25 | – | |
| | | | 2.3 | 2.3 | 2.0 | – | |
| | | $I_{OH}$ = −12 mA; $V_I$ = $V_{IH}$ | 2.3 | 2.3 | 1.8 | – | |
| | | | 2.7 | 2.7 | 2.2 | – | |
| | | $I_{OH}$ = −18 mA; $V_I$ = $V_{IH}$ | 2.3 | 2.3 | 1.7 | – | |
| | | | 3.0 | 3.0 | 2.4 | – | |
| | | $I_{OH}$ = −24 mA; $V_I$ = $V_{IH}$ | 3.0 | 3.0 | 2.2 | – | |
| $V_{OL}$ | Output LOW Voltage | $I_{OL}$ = 100 μA; $V_I$ = $V_{IL}$ | 0.9 – 4.5 | 0.9 – 4.5 | – | 0.2 | V |
| | | $I_{OL}$ = 0.5 mA; $V_I$ = $V_{IH}$ | 1.1 | 1.1 | – | 0.3 | |
| | | $I_{OL}$ = 2 mA; $V_I$ = $V_{IH}$ | 1.4 | 1.4 | – | 0.35 | |
| | | $I_{OL}$ = 6 mA; $V_I$ = $V_{IL}$ | 1.65 | 1.65 | – | 0.3 | |
| | | $I_{OL}$ = 12 mA; $V_I$ = $V_{IL}$ | 2.3 | 2.3 | – | 0.4 | |
| | | | 2.7 | 2.7 | – | 0.4 | |
| | | $I_{OL}$ = 18 mA; $V_I$ = $V_{IL}$ | 2.3 | 2.3 | – | 0.6 | |
| | | | 3.0 | 3.0 | – | 0.45 | |
| | | $I_{OL}$ = 24 mA; $V_I$ = $V_{IL}$ | 3.0 | 3.0 | – | 0.6 | |
| $I_I$ | Input Leakage Current | $V_I$ = $V_{CCA}$ or GND | 0.9 – 4.5 | 0.9 – 4.5 | −1.0 | 1.0 | μA |
| $I_{OFF}$ | Power−Off Leakage Current | $\overline{OE}$ = 0 V | 0<br>0.9 – 4.5 | 0.9 – 4.5<br>0 | −1.0<br>−1.0 | 1.0<br>1.0 | μA |
| $I_{CCA}$ | Quiescent Supply Current | $V_I$ = $V_{CCA}$ or GND; $I_O$ = 0, $V_{CCA}$ = $V_{CCB}$ | 0.9 – 4.5 | 0.9 − 4.5 | – | 2.0 | μA |
| $I_{CCB}$ | Quiescent Supply Current | $V_I$ = $V_{CCA}$ or GND; $I_O$ = 0, $V_{CCA}$ = $V_{CCB}$ | 0.9 – 4.5 | 0.9 − 4.5 | – | 2.0 | μA |
| $I_{CCA}$ + $I_{CCB}$ | Quiescent Supply Current | $V_I$ = $V_{CCA}$ or GND; $I_O$ = 0, $V_{CCA}$ = $V_{CCB}$ | 0.9 – 4.5 | 0.9 – 4.5 | – | 4.0 | μA |
| $\Delta I_{CCA}$ | Increase in $I_{CC}$ per Input Voltage, Other Inputs at $V_{CCA}$ or GND | $V_I$ = $V_{CCA}$ – 0.6 V;<br>$V_I$ = $V_{CCA}$ or GND | 4.5<br>3.6 | 4.5<br>3.6 | – | 10<br>5.0 | μA |
| $\Delta I_{CCB}$ | Increase in $I_{CC}$ per Input Voltage, Other Inputs at $V_{CCA}$ or GND | $V_I$ = $V_{CCA}$ – 0.6 V;<br>$V_I$ = $V_{CCA}$ or GND | 4.5<br>3.6 | 4.5<br>3.6 | – | 10<br>5.0 | μA |
| $I_{OZ}$ | I/O Tri−State Output Leakage Current | $T_A$ = 25°C, $\overline{OE}$ = 0$V_{CCA}$, $V_O$ = 0 to $V_{CCB}$ + 0.5 V | 0.9 – 4.5 | 0.9 – 4.5 | – | 1.0 | μA |
| | | $T_A$ = 25°C, $\overline{OE}$ = 0$V_{CCA}$, $V_O$ = 0 to 4.5 V | | | – | 75 | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

### TOTAL STATIC POWER CONSUMPTION ($I_{CCA}$ + $I_{CCB}$)

| | −40°C to +85°C | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | $V_{CCB}$ (V) | | | | | | | | | | |
| | 4.5 | | 3.3 | | 2.8 | | 1.8 | | 0.9 | | |
| $V_{CCA}$ (V) | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max | Unit |
| 4.5 | | 2 | | 2 | | 2 | | 2 | | < 1.5 | μA |
| 3.3 | | 2 | | 2 | | 2 | | 2 | | < 1.5 | μA |
| 2.8 | | < 2 | | < 1 | | < 1 | | < 0.5 | | < 0.5 | μA |
| 1.8 | | < 1 | | < 1 | | < 0.5 | | < 0.5 | | < 0.5 | μA |
| 0.9 | | < 0.5 | | < 0.5 | | < 0.5 | | < 0.5 | | < 0.5 | μA |

NOTE: Connect ground before applying supply voltage $V_{CCA}$ or $V_{CCB}$. This device is designed with the feature that the power−up sequence of $V_{CCA}$ and $V_{CCB}$ will not damage the IC.

### AC ELECTRICAL CHARACTERISTICS

| | | | −40°C to +85°C | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | $V_{CCB}$ (V) | | | | | | | | | | |
| | | | 4.5 | | 3.3 | | 2.8 | | 1.8 | | 1.5 | | |
| Symbol | Parameter | $V_{CCA}$ (V) | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max | Unit |
| $t_{PLH}$, $t_{PHL}$ (Note 1) | Propagation Delay, $A_n$ to $B_n$ | 4.5 | | 3.0 | | 3.2 | | 3.4 | | 3.7 | | 4.0 | nS |
| | | 3.6 | | 3.3 | | 3.5 | | 3.7 | | 4.0 | | 4.3 | |
| | | 2.8 | | 3.5 | | 3.7 | | 3.9 | | 4.2 | | 4.5 | |
| | | 1.8 | | 3.8 | | 4.0 | | 4.2 | | 4.5 | | 4.8 | |
| | | 1.5 | | 4.1 | | 4.3 | | 4.5 | | 4.8 | | 5.0 | |
| $t_{PZH}$, $t_{PZL}$ (Note 1) | Output Enable, $\overline{OE}$ to $B_n$ | 4.5 | | 4.4 | | 4.8 | | 5.2 | | 5.7 | | 6.2 | nS |
| | | 3.3 | | 4.7 | | 5.1 | | 5.5 | | 6.0 | | 6.5 | |
| | | 2.8 | | 4.9 | | 5.3 | | 5.7 | | 6.2 | | 6.7 | |
| | | 1.8 | | 5.2 | | 5.6 | | 6.0 | | 6.5 | | 7.0 | |
| | | 1.5 | | 5.5 | | 5.9 | | 6.3 | | 6.8 | | 7.3 | |
| $t_{PHZ}$, $t_{PLZ}$ (Note 1) | Output Disable, $\overline{OE}$ to $B_n$ | 4.5 | | 4.4 | | 4.8 | | 5.2 | | 5.7 | | 6.2 | nS |
| | | 3.3 | | 4.7 | | 5.1 | | 5.5 | | 6.0 | | 6.5 | |
| | | 2.8 | | 4.9 | | 5.3 | | 5.7 | | 6.2 | | 6.7 | |
| | | 1.8 | | 5.2 | | 5.6 | | 6.0 | | 6.5 | | 7.0 | |
| | | 1.5 | | 5.5 | | 5.9 | | 6.3 | | 6.8 | | 7.3 | |
| $t_{OSHL}$, $t_{OSLH}$ (Note 1) | Output to Output Skew, Data to Output | 4.1 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | nS |
| | | 3.6 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | |
| | | 2.8 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | |
| | | 1.8 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | |
| | | 1.2 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | | 0.15 | |

1. Propagation delays defined per Figures 3 and 4.

### CAPACITANCE

| Symbol | Parameter | Test Conditions | **Typ** (Note 2) | Unit |
|---|---|---|---|---|
| $C_{IN}$ | Control Pin Input Capacitance | $V_{CCA}$ = $V_{CCB}$ = 3.3 V, $V_I$ = 0 V or $V_{CCA/B}$ | 3.5 | pF |
| $C_{I/O}$ | I/O Pin Input Capacitance | $V_{CCA}$ = $V_{CCB}$ = 3.3 V, $V_I$ = 0 V or $V_{CCA/B}$ | 5.0 | pF |
| $C_{PD}$ | Power Dissipation Capacitance | $V_{CCA}$ = $V_{CCB}$ = 3.3 V, $V_I$ = 0 V or $V_{CCA}$, f = 10 MHz | 20 | pF |

2. Typical values are at $T_A$ = +25°C.
3. $C_{PD}$ is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from: $I_{CC(operating)} \cong C_{PD} \times V_{CC} \times f_{IN} \times N_{SW}$ where $I_{CC} = I_{CCA} + I_{CCB}$ and $N_{SW}$ = total number of outputs switching.

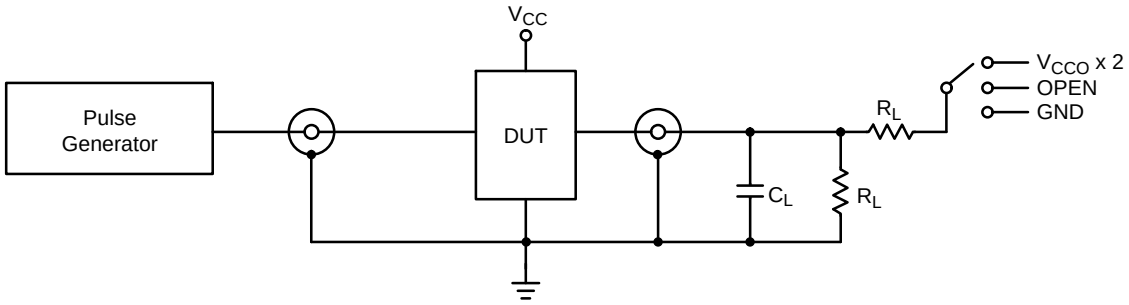
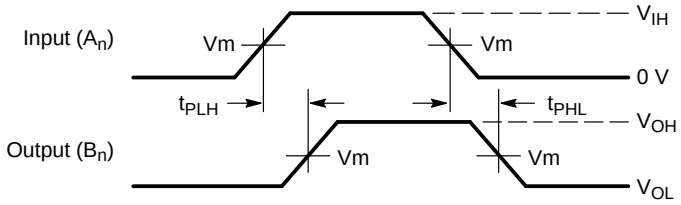
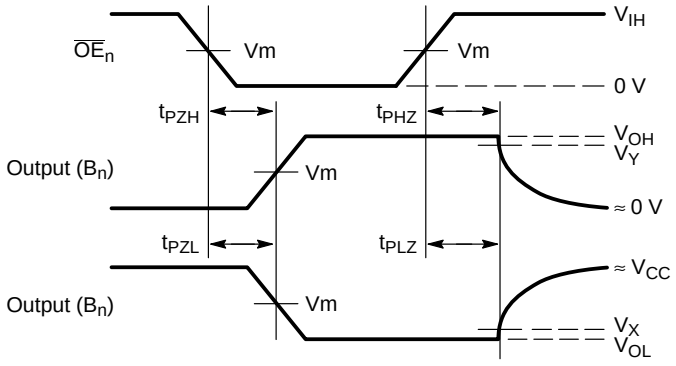



**Figure 3. AC (Propagation Delay) Test Circuit**

| Test | Switch |
|---|---|
| $t_{PLH}$, $t_{PHL}$ | OPEN |
| $t_{PLZ}$, $t_{PZL}$ | $V_{CCO}$ x 2 |
| $t_{PHZ}$, $t_{PZH}$ | GND |
| $C_L$ = 15 pF or equivalent (includes probe and jig capacitance)<br>$R_L$ = 2 kΩ or equivalent<br>$Z_{OUT}$ of pulse generator = 50 Ω | |




**Waveform 1 − Propagation Delays**
$t_R = t_F$ = 2.0 ns, 10% to 90%; f = 1 MHz; $t_W$ = 500 ns




**Waveform 2 − Output Enable and Disable Times**
$t_R = t_F$ = 2.0 ns, 10% to 90%; f = 1 MHz; $t_W$ = 500 ns

**Figure 4. AC (Propagation Delay) Test Circuit Waveforms**

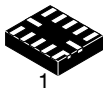
| Symbol | $V_{CC}$ | | | | |
|---|---|---|---|---|---|
| | 3.0 V – 4.5 V | 2.3 V – 2.7 V | 1.65 V – 1.95 V | 1.4 V – 1.6 V | 0.9 V – 1.3 V |
| $V_{mA}$ | $V_{CCA}/2$ | $V_{CCA}/2$ | $V_{CCA}/2$ | $V_{CCA}/2$ | $V_{CCA}/2$ |
| $V_{mB}$ | $V_{CCB}/2$ | $V_{CCB}/2$ | $V_{CCB}/2$ | $V_{CCB}/2$ | $V_{CCB}/2$ |
| $V_X$ | $V_{OL}$ x 0.1 | $V_{OL}$ x 0.1 | $V_{OL}$ x 0.1 | $V_{OL}$ x 0.1 | $V_{OL}$ x 0.1 |
| $V_Y$ | $V_{OH}$ x 0.9 | $V_{OH}$ x 0.9 | $V_{OH}$ x 0.9 | $V_{OH}$ x 0.9 | $V_{OH}$ x 0.9 |

# MECHANICAL CASE OUTLINE
## PACKAGE DIMENSIONS

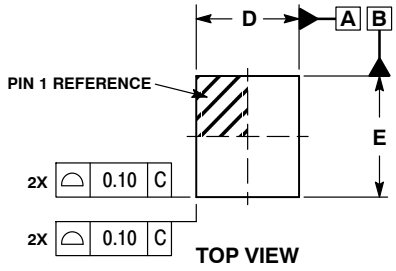
ON Semiconductor®

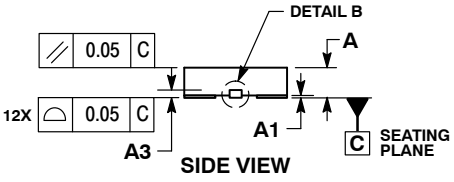
**UQFN12 1.7x2.0, 0.4P**
CASE 523AE−01
ISSUE A

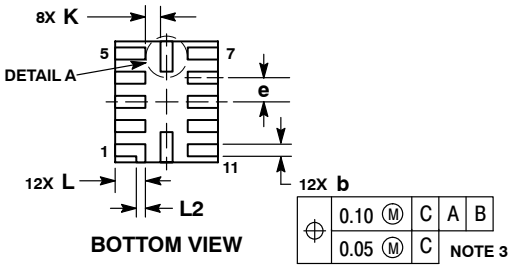
DATE 11 JUN 2007

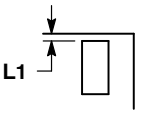


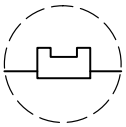
SCALE 4:1



DETAIL B
OPTIONAL CONSTRUCTION

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH 0.03 MAX ON BOTTOM SURFACE OF TERMINALS.
5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

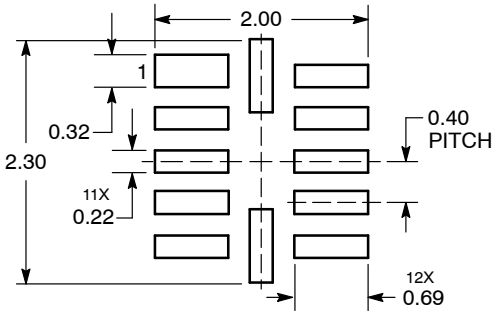
| | MILLIMETERS | |
|---|---|---|
| DIM | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A3 | 0.127 REF | |
| b | 0.15 | 0.25 |
| D | 1.70 BSC | |
| E | 2.00 BSC | |
| e | 0.40 BSC | |
| K | 0.20 | ---- |
| L | 0.45 | 0.55 |
| L1 | 0.00 | 0.03 |
| L2 | 0.15 REF | |

### GENERIC MARKING DIAGRAM*


XX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

### MOUNTING FOOTPRINT SOLDERMASK DEFINED




DIMENSIONS: MILLIMETERS

| | | | |
|---|---|---|---|
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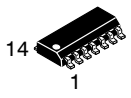
| DESCRIPTION: | UQFN12 1.7 X 2.0, 0.4P | | PAGE 1 OF 1 |

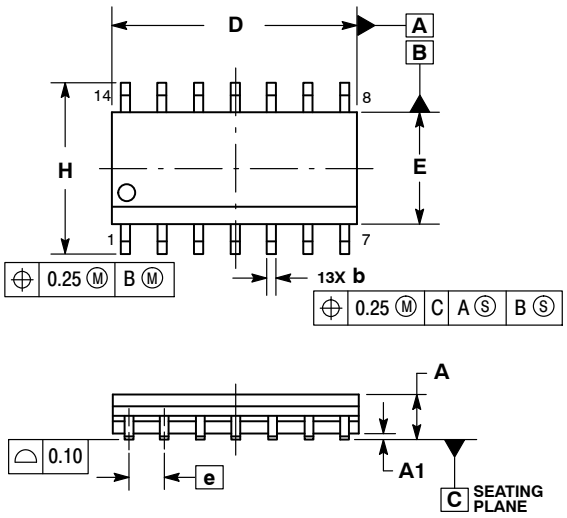
# MECHANICAL CASE OUTLINE
## PACKAGE DIMENSIONS

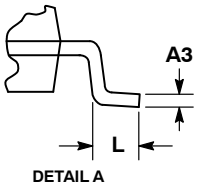


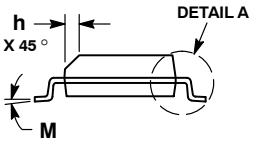

**SCALE 1:1**

**SOIC−14 NB**
CASE 751A−03
ISSUE L

DATE 03 FEB 2016



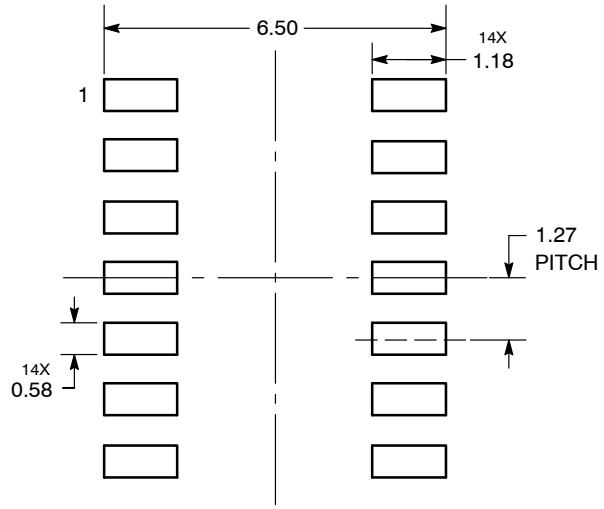




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

| | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 1.35 | 1.75 | 0.054 | 0.068 |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 |
| A3 | 0.19 | 0.25 | 0.008 | 0.010 |
| b | 0.35 | 0.49 | 0.014 | 0.019 |
| D | 8.55 | 8.75 | 0.337 | 0.344 |
| E | 3.80 | 4.00 | 0.150 | 0.157 |
| e | 1.27 BSC | | 0.050 BSC | |
| H | 5.80 | 6.20 | 0.228 | 0.244 |
| h | 0.25 | 0.50 | 0.010 | 0.019 |
| L | 0.40 | 1.25 | 0.016 | 0.049 |
| M | 0 ° | 7 ° | 0 ° | 7 ° |

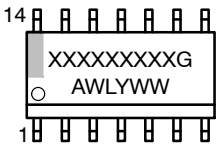
### SOLDERING FOOTPRINT*




DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### GENERIC MARKING DIAGRAM*




XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

**STYLES ON PAGE 2**

| | | | |
|---|---|---|---|
| **DOCUMENT NUMBER:** | **98ASB42565B** | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red. | |
| **DESCRIPTION:** | **SOIC−14 NB** | | **PAGE 1 OF 2** |

**SOIC−14**
CASE 751A−03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

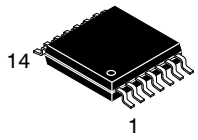
STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

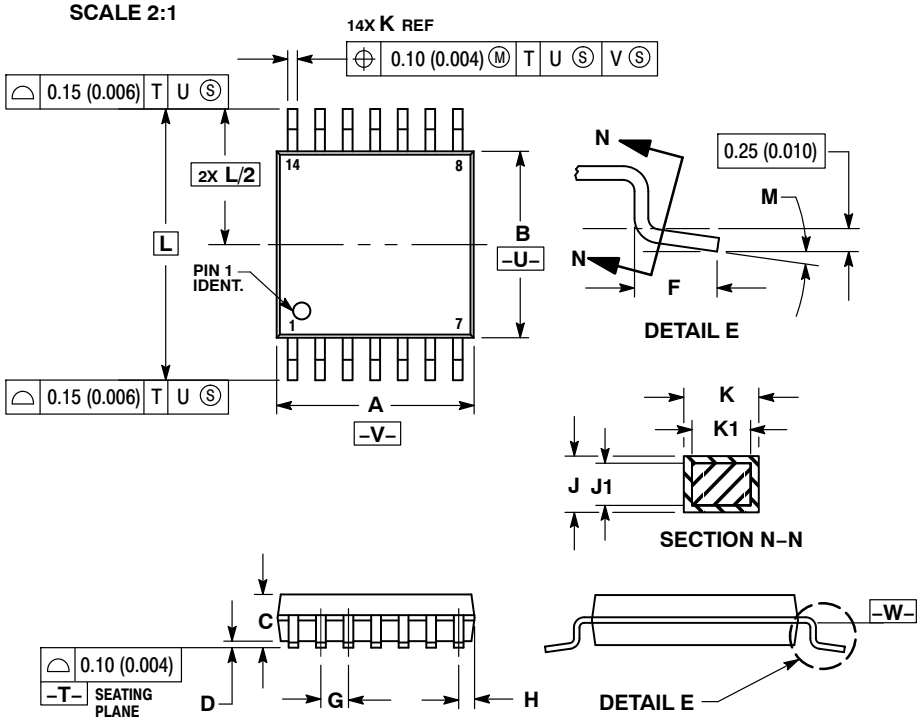
# MECHANICAL CASE OUTLINE
## PACKAGE DIMENSIONS

**TSSOP−14 WB**
CASE 948G
ISSUE C

DATE 17 FEB 2016



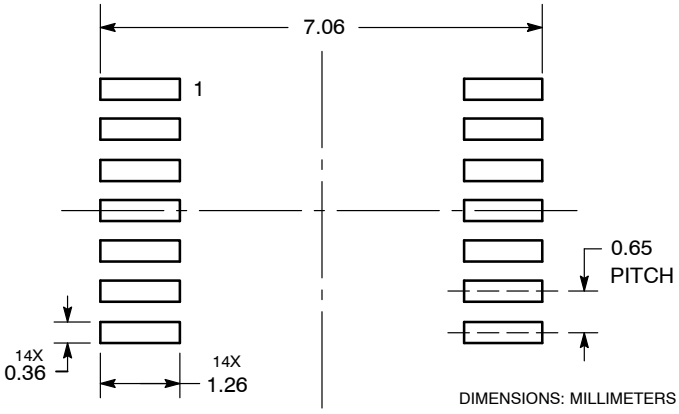

**SCALE 2:1**




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

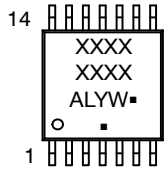
| | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 4.90 | 5.10 | 0.193 | 0.200 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | −−− | 1.20 | −−− | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.50 | 0.60 | 0.020 | 0.024 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0 ° | 8 ° | 0 ° | 8 ° |

### SOLDERING FOOTPRINT




DIMENSIONS: MILLIMETERS

### GENERIC MARKING DIAGRAM*




A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

| | | |
|---|---|---|
| **DOCUMENT NUMBER:** | **98ASH70246A** | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red. |
| **DESCRIPTION:** | **TSSOP−14 WB** | **PAGE 1 OF 1** |

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